

RECORDATION FORM COVER SHEET by Fax 703-306-5995

US Department of Commerce
Patent & Trademark Office

To the Honorable Commissioner of Patents and Trademarks:

Please record the attached original documents or copy thereof.

1. Name(s) of conveying parties:
Cherngye Hwang, San Jose, CA
Eun Row, San Jose, CA
Ning Shi, San Jose, CA
Eric (Yongjian) Sun, San Jose, CA

2. Name and address of receiving party:

**HITACHI GLOBAL STORAGE TECHNOLOGIES NETHERLANDS, B.V.,
Locatellikade 1,
Parnassustoren
1076 AZ Amsterdam,
The Netherlands**

Additional name(s) of conveying party(ies) attached Yes No

3. Nature of conveyance: **Assignment** Execution Date:

4. Application number(s) or patent number(s):

A. Patent Application No. (s) 10/651,632
B. Patent No. (s)

5. Name and address of party to whom correspondence concerning document should be mailed:

**G. Marlin Knight (#33,409)
Hoyt & Knight
PO Box 1320
Pioneer, CA 95666**

6. Total Number of applications and patents involved: **One**


7. Total fee (37 CFR 3.41).....\$ **40.00**

Authorized to be charged to deposit account 50-2587

8. Deposit Account Number: 50-2587

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

(x)  Date: Jan. 20, 2004
G. Marlin Knight #33,409

(Total number of pages including cover sheet, attachments, and document: 2)

ASSIGNMENT

Whereas, we:

INVENTOR
AND CITY

- 1. Cherngye Hwang, San Jose, CA
- 2. Eun Row, San Jose, CA
- 3. Ning Shi, San Jose, CA
- 4. Eric (Yongjian) Sun, San Jose, CA

have invented certain improvements in a

TITLE

Method for Depositing a Thin Film Adhesion Layer

and executed, respectively, a United States patent application therefor on

DATE THAT
INVENTOR
SIGNED THE
DECLARATION

- 1. 8/26/03 ; 2. 8/15/03 ; 3. 8/25/03 ; 4. 8/14/03
- 5. _____

Whereas, HITACHI GLOBAL STORAGE TECHNOLOGIES NETHERLANDS, B.V., having a place of business at Locatellikade 1, 1076 AZ Amsterdam, The Netherlands (hereinafter called HITACHI), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to HITACHI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to HITACHI, its successors and assigns; and we hereby agree that HITACHI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by HITACHI.

Signed and sealed

CITY, DATE

1. at San Jose on 8/26, 2003,


INVENTOR'S
SIGNATURE

 SIGNATURE
Cherngye Hwang


2. at San Jose on 8/15, 2003,

 SIGNATURE
Eun Row

3. at San Jose on 8/25, 2003,

 SIGNATURE
Ning Shi

4. at San Jose on 8/14, 2003,

 SIGNATURE
Eric (Yongjian) Sun